

AMENDMENTS TO THE CLAIMS:

Claims 1-3 (Cancelled)

4. (Original) An electronic component placement method comprising:

recognizing a position of an electronic component by capturing, via a feeder camera unit, an image of said electronic component while in a feeder;

positioning said electronic component relative to a takeout and transfer head based on a positional recognition result of said electronic component obtained by recognizing said position of said electronic component while in said feeder;

using said takeout and transfer head to remove said electronic component from said feeder at a feeding position, and transferring said electronic component to a receiving position;

using a placement head to receive said electronic component from said takeout and transfer head at said receiving position;

recognizing a position of said electronic component by capturing, via a placement head camera unit, an image of said electronic component from beneath said placement head while said electronic component is held by said placement head

positioning said electronic component, while held by said placement head, relative to a board, while held by a board holder based on a positional recognition result of said electronic component obtained by recognizing said position of said electronic component while held by said placement head;

placing said electronic component onto said board; and

prior to capturing said image of said electronic component via said placement head camera unit, moving said takeout and transfer head from said receiving position to a position where capturing of said image by said placement head camera unit is not hindered.

5. (Original) The method according to claim 4, wherein capturing an image of said electronic component via a feeder camera unit comprises capturing said image of said electronic component via a feeder camera unit that is positioned above said feeder, and further comprising:

prior to capturing said image of said electronic component via said feeder camera unit, moving said takeout and transfer head from said feeding position to a position where capturing of said image via said feeder camera unit is not hindered.

Claims 6-8 (Cancelled)

9. (Original) An electronic component placement method comprising:

recognizing a position of an electronic component by capturing, via a feeder camera unit, an image of said electronic component while in a feeder;

positioning said electronic component relative to a takeout and transfer head based on a positional recognition result of said electronic component obtained by recognizing said position of said electronic component while in said feeder;

using a takeout and transfer head to remove said electronic component from said feeder at a feeding position, and to flip said electronic component while transferring said electronic component to a receiving position;

positioning said electronic component, after having been removed from said feeder, relative to a placement head;

using said placement head to receive said electronic component, after having been positioned relative to said placement head, from said takeout and transfer head at said receiving position;

recognizing a position of said electronic component by capturing, via a placement head camera unit, an image of said electronic component from beneath said placement head while said electronic component is held by said placement head,;

positioning said electronic component, while held by said placement head, relative to a board, while held by a board holder, based on a positional recognition result of said electronic component obtained by recognizing said position of said electronic component while held by said placement head; and

placing said electronic component onto said board after said electronic component has been positioned relative to said board.

10. (Original) The method according to claim 9, further comprising:

capturing, via a takeout and transfer head camera unit, an image of said electronic component, while held by said takeout and transfer head during removal of said electronic component from said feeder and transferring of said electronic component to said receiving position; and

positioning said placement head against said electronic component, while held by said takeout and transfer head at said receiving position, by controlling at least one of a takeout and transfer device that is to control movement of said takeout and transfer head and a placement head driving mechanism that is to control movement of said placement head, based on said image captured via said takeout and transfer head camera unit.

11. (Original) The method according to claim 9, wherein

positioning said electronic component relative to said placement head comprises positioning said electronic component, while held by said takeout and transfer head during removal of said electronic component from said feeder and transferring of said electronic component to said receiving position, to a normal position by utilizing a pre-centering device.

Claims 12-16 (Cancelled)